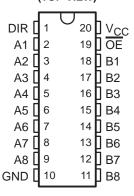
SCBS680A - MARCH 1997 - REVISED MAY 1997

- Outputs Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- High-Impedance State During Power Up and Power Down
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds 2000 V Per MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Thin Very Small-Outline (DGV) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

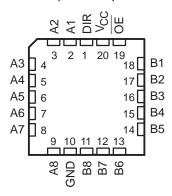
description

These octal transceivers and line drivers are designed for asynchronous communication between data buses. The devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

SN54ABTR2245 . . . J PACKAGE SN74ABTR2245 . . . DB, DGV, DW, N, OR PW PACKAGE (TOP VIEW)



SN54ABTR2245 . . . FK PACKAGE (TOP VIEW)



Both the A-port and B-port outputs, which are designed to sink up to 12 mA, include equivalent 25- Ω series resistors to reduce overshoot and undershoot.

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTR2245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTR2245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation



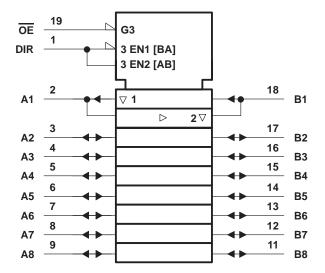
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.



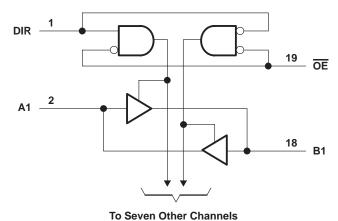
SCBS680A - MARCH 1997 - REVISED MAY 1997

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

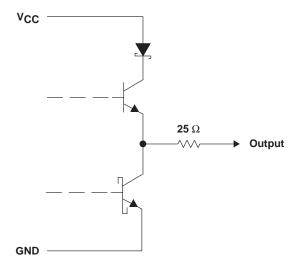
logic diagram (positive logic)





SCBS680A - MARCH 1997 - REVISED MAY 1997

output schematic



All resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Input voltage range, VI (except I/O ports) (see I	Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high	or power-off state, VO	
Current into any output in the low state, IO		30 mA
Input clamp current, I_{IK} ($V_I < 0$)		–18 mA
Output clamp current, I _{OK} (V _O < 0)		
Package thermal impedance, θ _{JA} (see Note 2):	: DB package	115°C/W
	DGV package	146°C/W
	DW package	97°C/W
	N package	67°C/W
	PW package	128°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

SN54ABTR2245, SN74ABTR2245 OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

SCBS680A - MARCH 1997 - REVISED MAY 1997

recommended operating conditions (see Note 3)

			SN54AB1	ΓR2245	SN74AB1	TR2245	LINUT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	3	2		V
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	0	Vcc	0	Vcc	V	
IOH	High-level output current		1	-12		-12	mA
loL	Low-level output current		3	12		12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	0	5		5	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		2 200		200		μs/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

SN54ABTR2245, SN74ABTR2245 OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

SCBS680A - MARCH 1997 - REVISED MAY 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST COA	IDITIONS	Т	T _A = 25°C			SN54ABTR2245		SN74ABTR2245	
PAR	ANICIER	TEST CON	IDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -1 \text{ mA}$	3.35			3.3		3.35		
Voн		$V_{CC} = 5 V$,	I _{OH} = -1 mA	3.85			3.8		3.85		V
VОН		V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$				3		3.1		V
Vo		VCC = 4.5 V	$I_{OH} = -12 \text{ mA}$	2.6					2.6		
VOL		V _{CC} = 4.5 V	I _{OL} = 8 mA			0.65		0.8		0.65	V
VOL		VCC = 4.0 V	I _{OL} = 12 mA			0.8				0.8	•
V _{hys}					100						mV
	Control inputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V}, \text{ V}_{I}$	= V _{CC} or GND			±1		±1		±1	μΑ
l _l	A or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}$ $V_I = V_{CC} \text{ or GND}$	/,			±20		±20		±20	μΑ
lozH [‡]		$\frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}$	$V_{0} = 2.7 V_{0}$			10		10		μΑ	
l _{OZL} ‡		$\frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}$	$V_{0} = 0.5 V_{0}$			-10	, Q , Q	-10		-10	μΑ
lozpu§	}	$\frac{\text{VCC}}{\text{OE}} = 0 \text{ to } 2.1 \text{ V, V}_{\text{O}}$) = 0.5 V to 2.7 V,			±50	±50			±50	μΑ
I _{OZPD} §	i	$\frac{V_{CC}}{OE} = 2.1 \text{ V to } 0, V_{CC}$) = 0.5 V to 2.7 V,			±50	Q	±50		±50	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μА
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ
IOI		V _{CC} = 5.5 V,	V _O = 2.5 V	-25		-100	-25	-100	-25	-100	mA
		V _{CC} = 5.5 V,	Outputs high		1	250		250		250	μΑ
ICC	A or B ports	$I_{O} = 0$,	Outputs low		24	32		32		32	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.5	250		250		250	μА
	Data inputs	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5	
Δl _{CC} #	Data inputs	Other inputs at VCC or GND	Outputs disabled			0.05		0.05		0.05	mA
	Control inputs	$V_{CC} = 5.5 \text{ V}$, One in Other inputs at V_{CC}				1.5		1.5		1.5	
Ci		V _I = 2.5 V or 0.5 V			pF						
C _{io}		$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			6						pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

[§] This parameter is characterized but not production tested.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#]This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

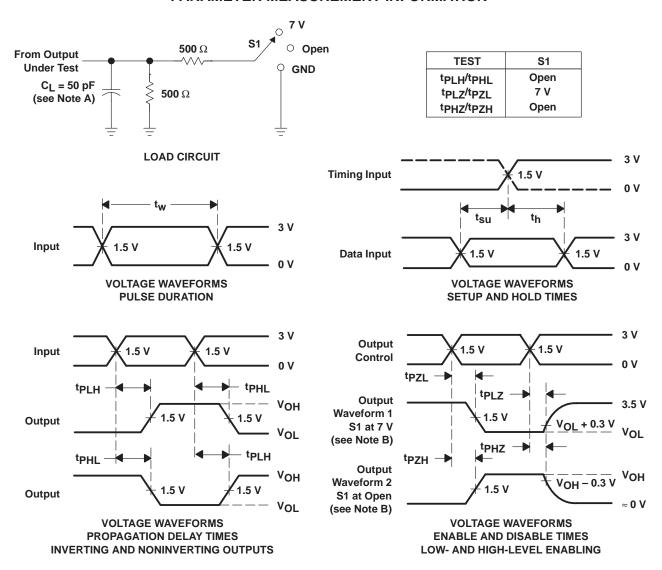
SN54ABTR2245, SN74ABTR2245 OCTAL TRANSCEIVERS AND LINE/MEMORY DRIVERS WITH 3-STATE OUTPUTS

SCBS680A - MARCH 1997 - REVISED MAY 1997

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO (INPUT) (OUTPUT)		V _{CC} = 5 V, T _A = 25°C			SN54ABT	R2245	SN74AB1	UNIT	
	(INFOT)	(001F01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A or B	P.or A	1	2.5	3.4	1	4	1	3.8	20
^t PHL	AUIB	B or A	1	3.2	4.2	1 (4.6	1	4.5	ns
^t PZH	ŌĒ	A or B	1.5	3.6	4.9	1.5	6.3	1.5	6.1	20
^t PZL	OE	AUIB	1.5	3.9	5.3	1.5	6.6	1.5	6.3	ns
^t PHZ	ŌĒ	A or B	1.5	3.6	4.7	1.5	5.5	1.5	5.3	20
t _{PLZ}	OE	AUID	1.5	3.3	4.4	1.5	4.9	1.5	4.8	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE MATERIALS INFORMATION

www.ti.com 12-Aug-2013

TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTR2245DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ABTR2245PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

www.ti.com 12-Aug-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTR2245DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ABTR2245PWR	TSSOP	PW	20	2000	367.0	367.0	38.0

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products Applications

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive Communications and Telecom **Amplifiers** amplifier.ti.com www.ti.com/communications **Data Converters** dataconverter.ti.com Computers and Peripherals www.ti.com/computers **DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps

DSP **Energy and Lighting** dsp.ti.com www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical logic.ti.com Logic Security www.ti.com/security

Power Mgmt power.ti.com Space, Avionics and Defense www.ti.com/space-avionics-defense

Microcontrollers microcontroller.ti.com Video and Imaging www.ti.com/video

RFID www.ti-rfid.com

OMAP Applications Processors www.ti.com/omap TI E2E Community e2e.ti.com

Wireless Connectivity <u>www.ti.com/wirelessconnectivity</u>